瀚荃股份有限公司
CviLux Corporation

CVILUX
2020.08.27
ISSUED

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CJ33 Series Board Mound Telephone Jack	SPEC.NO.: SPCJ065B
REVISIONS	ECNT120188		PAGE: 1 / 4

1. SCOPE:
This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:
MIL - STD - 202 Methods for test of connectors for electronic equipment
EIA - 364 Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CJ3388*11SP

4. SHAPE, CONSTRUCTION AND DIMENSIONS
See attached drawings

5. MATERIALS
See attached drawings

6. ACCOMMODATED P.C.BOARD
6.1 Thickness: 1.6 mm (.063″)
6.2 P.C. Board Layout: See attached drawings

REVIEWED : Eisley APPROVED : Sun VERIFIED : Michelle .

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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.5 A Max 150 V AC (r.m.s.)
7.2	Contact Resistance	Open circuit of DC 20 mV max. 100 mA max. EIA-364-23B	Less than 20 mΩ Max. (Initial) Less than 30 mΩ Max. (Final)
7.3	Dielectric strength	Test between adjacent circuits of unmated connector. When applied AC 1000 V 1 minute between adjacent contacts. 1.5KVrms at 60Hz or 2250VDC, 1 minute between shield and contacts EIA-364-20B	No change
7.4	Insulation Resistance	When applied DC 500 V between adjacent terminal or ground EIA-364-21C	More than 500 MΩ Max. (Initial) More than 200 MΩ Max. (Final)

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact Normal force	Individually pin of contact area EIA-364-04A	0.1Kgf Min.
8.2	Durability	Connector shall be subjected to 750 cycles of insertion and withdrawal EIA-364-09C	Appearance: No damage Contact resistance Less than 30 mΩ Max.
8.3	Mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed EIA-364-13B	2 contacts: 1.6 Kgf Max. 4 contacts: 1.8 Kgf Max 6 contacts: 2.1 Kgf Max 8 contacts: 2.3 Kgf Max 10 contacts: 2.5 Kgf Max

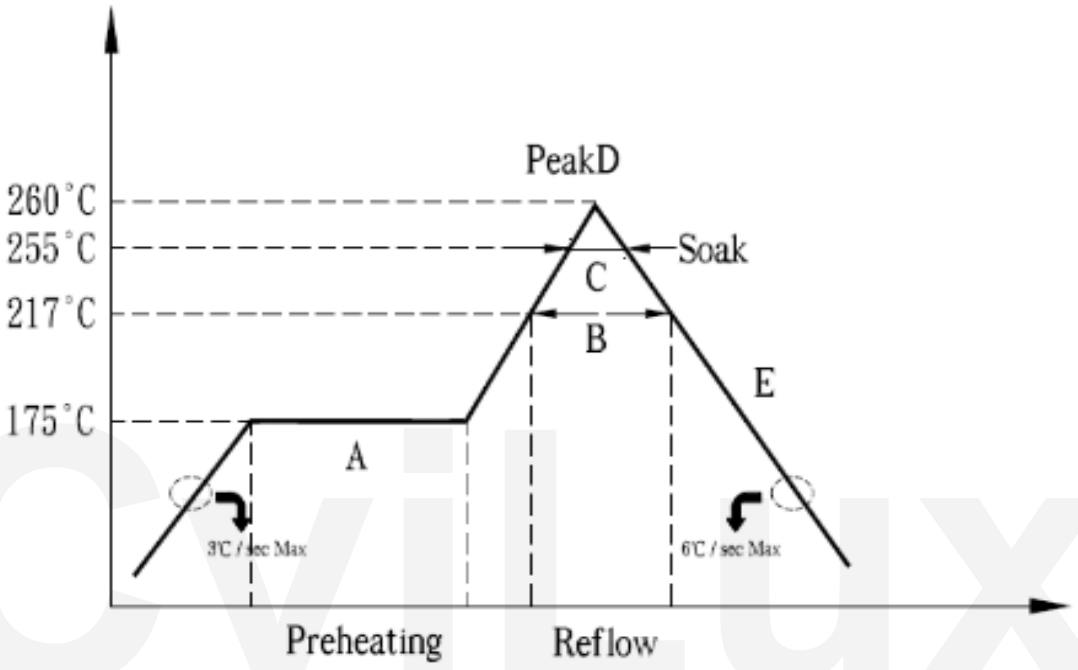
9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Humidity test	At a temperature of 40±2°C and relative humidity of 90-95% for 96 hours EIA-364-17B	Appearance: No damage Contact resistance Less than 30 mΩ Max.
9.2	Temperature Life	Exposing in a heat chamber at a temperature of 65±2°C for 96 hours EIA-364-17B	Appearance: No damage Contact resistance Less than 30 mΩ Max. Dielectric strength: To pass para 7-3
9.3	Salt spray	Temperature: 35 ± 3°C Solution: 5 ± 1% Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage on function Contact resistance: Less than twice of initial
9.4	Solder ability	Soldering time: 5±0.5 second Soldering pot: 245± 5°C	Minimum: 95% of immersed area
9.5	Resistance to soldering heat	Refer Reflow temperature profile(11.1)	Appearance: No damage

10. OPERATING TEMPERATURE RANGE: -40 to + 85°C

11. Recommended IR Reflow Temperature Profile:

11.1 Using Lead-Free Solder Past



- A : Pre-Heating (175+/-25°,120+/-60 Sec.)
- B : Reflow (217°C,60~150 Sec)
- C : Soak (235°C+5°C,24~36 Sec(30+/-20%))
- D : Max. Temp (260°C,10 Sec MAX)
- E : 6°C/sec Max